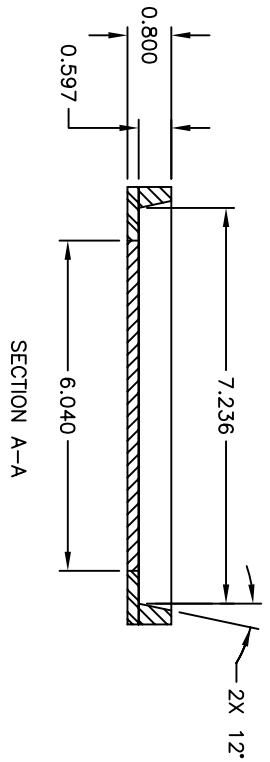
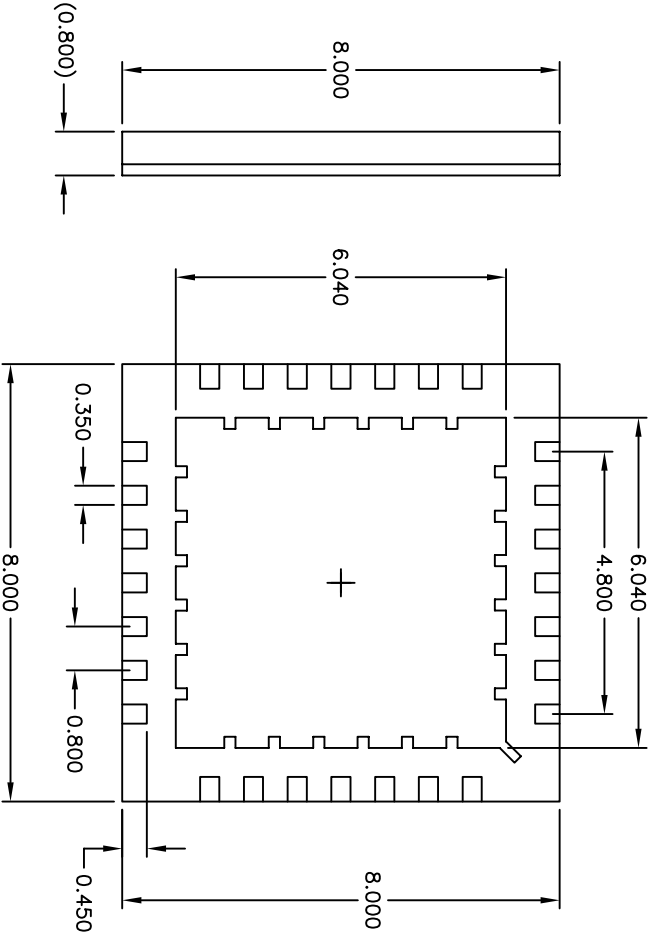
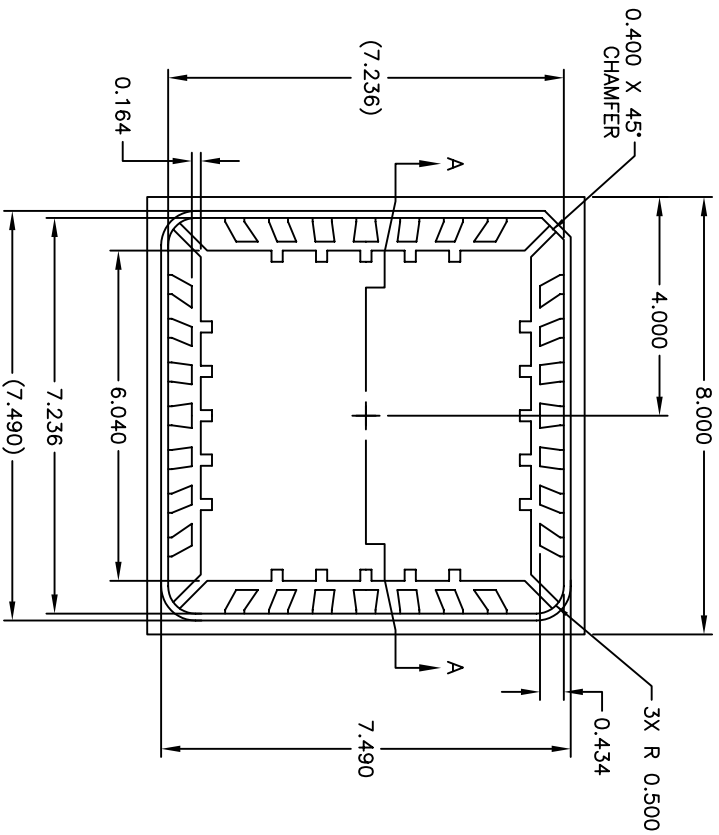


REVISIONS			APPROVED
EON NO.	DATE	DESCRIPTION	D.BENANDIO
10451	11/22/05	PRODUCTION RELEASE	



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FINISH: FULL GOLD PLATE.
 3. LEAD FRAME: COPPER, 194 FH.
 4. LEAD THICKNESS: 0.2030 ±.0076.
 5. DIE PAD: 6.040 X 6.040.
 6. JEDEC OUTLINE: MO-220 (VLLB-1).



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
 TOLERANCES ARE: X.XXX ± 0.15 X.XXXX ± 0.010 ANGLES: ± 1°
 DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	11/21/05
APP BY	P. FLASKERUD	DATE	11/21/05
CUSTOMER	---		

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28 Lead 8mm x 8mm
 MLP Open-Pak

SIZE	PART NO.	REV
A	MLP8X8-28-OP-01	1
SCALE	NONE	
FILE	MLP8X8-28-OP-01-R1.DWG	
SHEET	1 OF 1	